

2-25-02

PATENT

Docket No. 5853-224

02/22/02

PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents
BOX PATENT APPLICATION
 Washington, DC 20231

Transmitted herewith for filing of the patent application of:

Inventor(s): Rajiv K. Singh
 Seung-Mahn Lee

for **SLURRY AND METHOD FOR CHEMICAL MECHANICAL POLISHING OF METAL STRUCTURES
 INCLUDING REFRACTORY METAL BASED BARRIER LAYERS**

are the following:

Specification, including Abstract
 10 Sheets of drawing (3 sets)
 X Executed Declaration and Power of Attorney
 X Assignment with Recordation Cover Sheet
 X Other: 2 postcards

CLAIMS AS FILED

FOR	NO. FILED	NO. EXTRA
Basic Fee		
Total Claims	71	51
Indep Claims	6	3
multiple dependent claim present		No

If the difference in Col. 1 is less than zero, enter "0" in Col. 2

Assignment Recordation

Small Entity

RATE	FEE
	\$ 370.00
x \$ 9 =	\$ 459.00
x \$ 42 =	\$126.00
x \$135 =	\$
TOTAL	\$ 955.00
	\$ 40.00

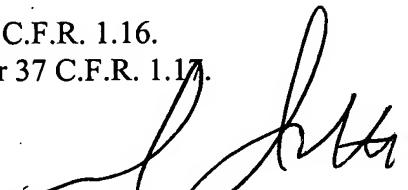
Other than a Small Entity

RATE	FEE
	\$ 740.00
x \$ 18 =	\$
x \$ 84 =	\$
x \$270 =	\$
TOTAL	\$

X You are hereby authorized to charge \$955.00 to Deposit Account 50-0951.
 X The Commissioner is hereby authorized to charge any underpayment of the following fees
 associated with this communication or credit any overpayment to Deposit Account No. 50-0951.
 A duplicate of this sheet is enclosed.
 X Any additional filing fees required under 37 C.F.R. 1.16.
 X Any patent application processing fees under 37 C.F.R. 1.17.

02/22/02

Date


 Neil R. Jetter
 Registration No. 46,803

11002 U.S. PRO
 10/08/2010
 02/22/02